

WORKPIECE PROCESSING METHOD

ABSTRACT OF THE DISCLOSURE

Disclosed herein is a workpiece processing method including: a step of applying a laser beam of such a wavelength as to be transmitted through the workpiece to the workpiece from a back surface side along division lines, to form first modified layers which are not cracked vertically and lower ends of which are located slightly on the back surface side as compared to a height position corresponding to a finished thickness of chips; a step of applying a laser beam of such a wavelength as to be transmitted through the workpiece to the workpiece from the back surface side along the division lines, to form second modified layers cracked vertically on the back surface side of the first modified layers; and a step of grinding the back surface of the workpiece to form the workpiece to the finished thickness of the chips, and to divide the workpiece into the chips, with the second modified layers as start points.

FIGURE 8